Organizers

VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM)
Dr.-Ing. Ronald Schnabel
Stresemannallee 15
60596 Frankfurt/Main, Germany
Phone: +49-69-6308 227
Fax: +49-69-6308 9828
E-Mail: gmm@vde.com

In cooperation with:

UBC Microelectronics
Dr. Uwe Behringer
Auf den Beeten 5
72119 Ammerbuch, Germany
Phone: +49-171-455-3196
Fax: +49-7073-50216
E-Mail: uwe.behringer.ubc@t-online.de

Venue:
Hilton Hotel
in Dresden

Dresden at
the River Elbe

The EMLC 2016 International Program Committee

Conference Chair	Jo Finders, ASML, Veldhoven, The Netherlands
Co-Conference Chairs	Brid Connolly, Toppan Photomasks GmbH, Dresden, Germany Chris Gale, Applied Materials, Dresden, Germany Naoya Hayashi, DNP, Saitama, Japan
Program Chairs	Uwe Behringer, UBC Microelectronics Ammerbuch, Germany Ines Stolberg, Vistec Electron Beam, Jena, Germany Daniel Sarlette, Infineon, Dresden, Germany Rolf Seltmann, Globalfoundries, Dresden, Germany

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Carola Blaesing, Carl Zeiss SMS GmbH, Jena, Germany
Parkson Chen, Taiwan Mask Corp., Hsinchu,Taiwan
Natalia Davydova, ASML, Veldhoven, The Netherlands
Dave Farrar, HOYA Corporation, London, UK
Bertrand Le Gratiet, ST Microelectronics, Crolles, Cedex, France
Rik Jonckheere, IMEC, Leuven, Belgium
Barbara Lauche, Photronics MZD GmbH, Dresden, Germany
Carlos Lee, EPIC, Brussels, Belgium
Harry Levinson, Globalfoundries, Santa Clara, CA, USA
Hans Loeschner, IMS Nanofabrication AG, Vienna, Austria
Jan Hendrik Peters, Carl Zeiss SMS GmbH, Jena, Germany
Chris Progler, Photronics Inc., USA
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Thomas Scheruebl, Carl Zeiss SMS GmbH, Jena, Germany
Ronald Schnabel, VDE/VDI-GMM, Frankfurt, Germany
Steffen Schulze, Mentor Graphics Corp. Wilsonville, OR, USA
Jacques Waelpoel, ASML, Veldhoven, Netherlands
Jim Wiley, ASML US Inc., Santa Clara, CA, USA
John Whittey, Oakdale CA, USA.
Carlton Willson, University of Texas, Austin, TX, USA
Hermann Wolf, Photronics MZD GmbH, Dresden, Germany
Stefan Wurm, SEMATECH, Albany , NY, USA
Larry Zurbrick, Agilent Technologies, Santa Clara, CA, USA

Cover picture: Courtesy of Toppan Photomasks

GMM VDE/VDI-GESELLSCHAFT
MIKROELEKTRONIK, MIKROSYSTEM-
UND FEINWERKTECHNIK

Call for Papers

The 32nd European Mask and Lithography Conference EMLC 2016

June 21 – 22, 2016
Hilton Hotel
Dresden, Germany

www.EMLC2016.com

VDI

VDE

The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

32nd European Mask and Lithography Conference, EMLC 2016

at the Hilton Hotel in Dresden, Germany
June 21 - June 22, 2016

The focus of this 2-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

Conference Schedule

The conference will be opened with a Keynote Session on Tuesday, June 21, 2016 at 09:00 a.m. and close on Wednesday, June 22, 2016, late afternoon. The Poster Session will be held on Tuesday evening followed by the Conference Banquet Dinner at the Pulverturm in Dresden.

Technical Exhibition

On Tuesday and Wednesday (June 21st and 22nd 2016) there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the **enclosed registration** form to the Conference Exhibition Organization as soon as possible, since exhibition space is limited.

Exhibition Organization

Dr. Uwe Behringer,
UBC Microelectronics,
Auf den Beeten 5,
D-72119 Ammerbuch, Germany
Phone: +49-171-4553196
Fax: +49-7073-50216
E-Mail: uwe.behringer.ubc@t-online.de

Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including figures, diagrams, formatted text as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2016.com
There you will find a link for the submission of papers

■ **Deadline for Abstracts: Friday, March 25th 2016**

! **By submitting an abstract you agree to**

- Present your work in person at the conference and
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **April 4th 2016**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript as early as possible but not later than the

■ **Deadline for Manuscripts: camera ready June 13th 2016**

Further information on the submission procedure can be found at **www.emlc2016.com**

All manuscripts will be subjected to a critical peer review before they are accepted for publication.
Please note that late submissions may not be published.

Manuscripts will be published by VDE Verlag in cooperation with SPIE Digital Library.

Conference Topics

Presentations are solicited for the following and related topics:

Mask Manufacturing

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application

- Double Patterning
- DSA (Directed Self-Assembly)
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write/ML^2, Maskless Technologies

Mask and Lithography Equipment

- Mask Manufacturing

Semiconductors in MEMS Applications

Patterned Media